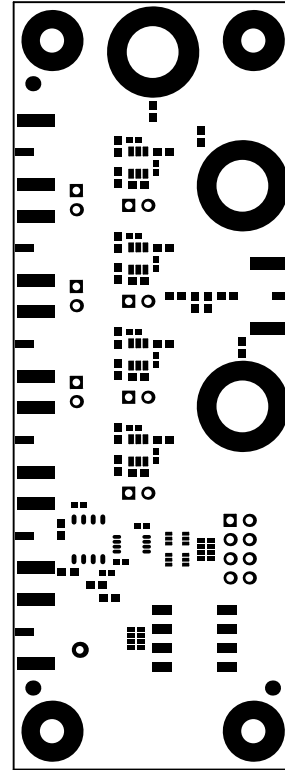
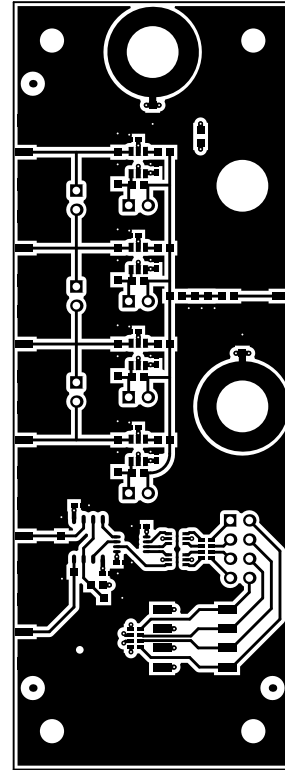


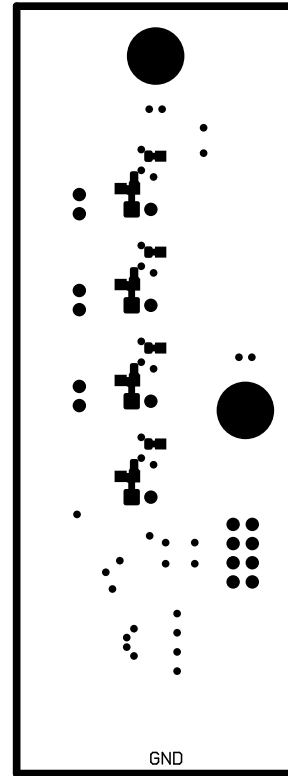
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01565	REV: E2	SUN REV: Not In VersionControl
LAYER NAME = Top Overlay	TID #: TIDA-01565		
PLOT NAME = Top Overlay	GENERATED : 6/7/2018	9:02:22 AM	TEXAS INSTRUMENTS



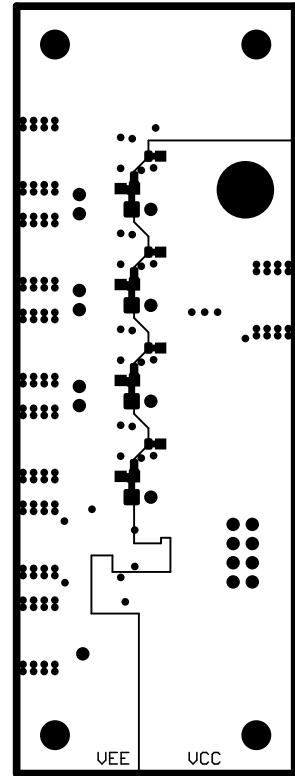
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01565	REV: E2	SUN REV: Not In VersionControl
LAYER NAME = Top Solder	TID #: TIDA-01565		
PLOT NAME = Top Solder Mask	GENERATED : 6/7/2018	9:02:23 AM	TEXAS INSTRUMENTS



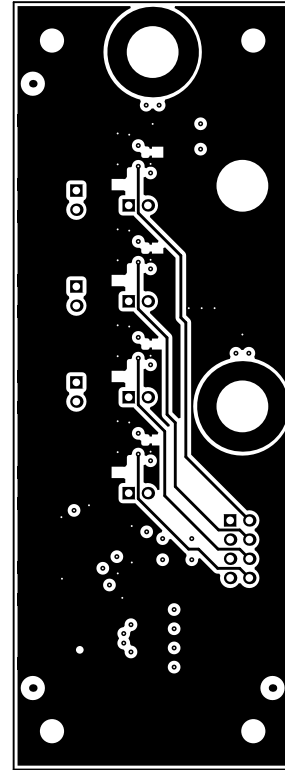
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01565	REV: E2	SUN REV: Not In VersionControl
LAYER NAME = Top Layer L1	TID #: TIDA-01565		
PLOT NAME = Top Layer L1	GENERATED : 6/7/2018	9:02:24 AM	TEXAS INSTRUMENTS



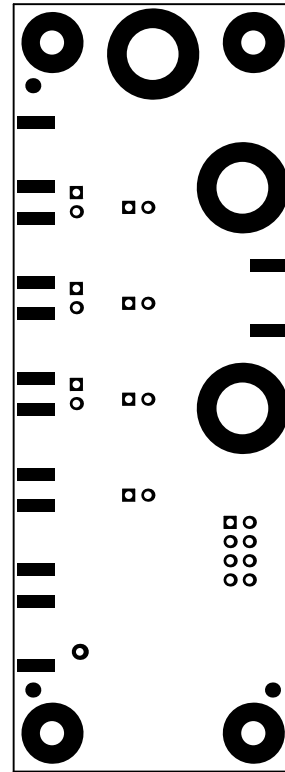
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01565	REV: E2	SUN REV: Not In VersionControl
LAYER NAME = GND L2	TID #: TIDA-01565		
PLOT NAME = GND L2	GENERATED : 6/7/2018	9:02:25 AM	TEXAS INSTRUMENTS



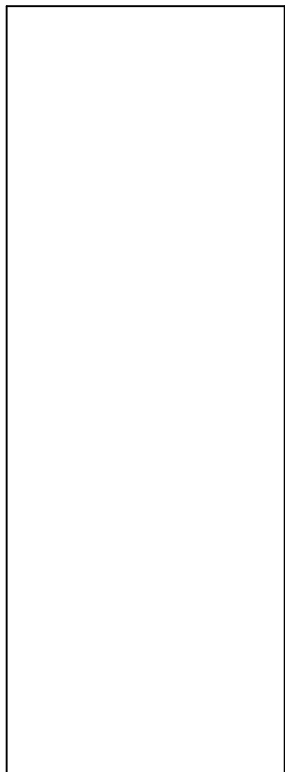
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01565	REV: E2	SUN REV: Not In VersionControl
LAYER NAME = Power L3	TID #: TIDA-01565		
PLOT NAME = Power L3	GENERATED : 6/7/2018	9:02:26 AM	TEXAS INSTRUMENTS



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01565	REV: E2	SUN REV: Not In VersionControl
LAYER NAME = Bottom Layer L4	TID #: TIDA-01565		
PLOT NAME = Bottom Layer L4	GENERATED : 6/7/2018	9:02:27 AM	TEXAS INSTRUMENTS

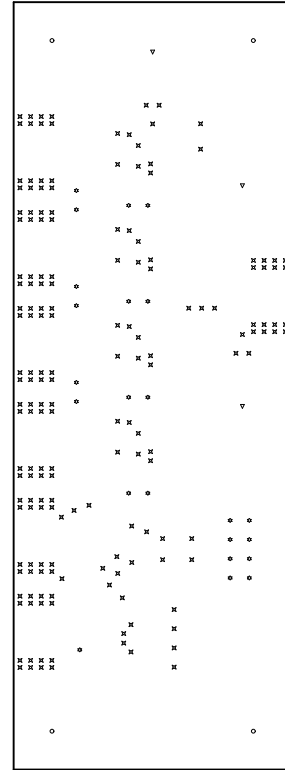


ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01565	REV: E2	SUN REV: Not In VersionControl
LAYER NAME = Bottom Solder	TID #: TIDA-01565		
PLOT NAME = Bottom Solder Mask	GENERATED : 6/7/2018	9:02:28 AM	TEXAS INSTRUMENTS



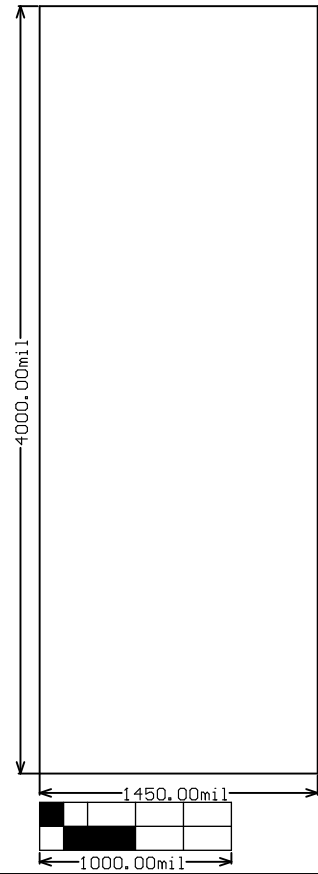
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01565	REV: E2	SUN REV: Not In VersionControl
LAYER NAME = Bottom Overlay	TID #: TIDA-01565		
PLOT NAME = Bottom Overlay	GENERATED : 6/7/2018	9:02:29 AM	TEXAS INSTRUMENTS





Symbol	Quantity	Finished Hole Size	Plated	Hole Type	Drill Layer Pair	Hole Tolerance
✱	175	10.00mil (0.254mm)	PTH	Round	Top Layer L1 - Bottom Layer L4	
☆	23	40.00mil (1.016mm)	PTH	Round	Top Layer L1 - Bottom Layer L4	
○	4	125.98mil (3.200mm)	PTH	Round	Top Layer L1 - Bottom Layer L4	
▽	3	270.00mil (6.858mm)	PTH	Round	Top Layer L1 - Bottom Layer L4	
	205 Total					

ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01565	REV: E2	SUN REV: Not In VersionControl
LAYER NAME = Drill Drawing	TID #: TIDA-01565		
PLOT NAME = Drill Drawing	GENERATED : 6/7/2018	9:02:30 AM	TEXAS INSTRUMENTS



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01565	REV: E2	SUN REV: Not In VersionControl
LAYER NAME = M2 Board Dimensions	TID #: TIDA-01565		
PLOT NAME = Board Dimensions	GENERATED : 6/7/2018	9:02:33 AM	TEXAS INSTRUMENTS

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